

SESSION 4b:
PROCESS – LITHOGRAPHY
Chairs: Robert Mohondro, *Plasma-Therm LLC*
Kamal Alavi, *Raytheon*

This session has four papers that deal with practical aspects of thick photo resist and BCB in the backend manufacturing of compound semiconductors. The first paper from TriQuint discusses tradeoffs between spun on vs. dry film lamination of thick photo resist. The second paper, from Northrop Grumman, deals with the effect of exposure mode on feature resolution for >10 um thick BCB. The third paper, from TriQuint, shows a new method for “Automated Skiplot Sampling for Photoresist Thickness Measurements”, which aids in productivity. The last paper, also from TriQuint, discusses how use of DMAIC (Define, Measure, Analyze, Improve and Control) method results in enhanced adhesion of SU8 and thus improves the final module yield.

